

L Number	Hits	Search Text	DB	Time stamp
1	738	(wafer or substrate) near2 (plate) and (plate) near6 (slot or groove or slit or notch) near6 (position or positioning or securing or positioned or aligning or aligned)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:58
2	4	((wafer or substrate) near2 (plate) and (plate) near6 (slot or groove or slit or notch) near6 (position or positioning or securing or positioned or aligning or aligned)) and (rta or rtp or rapid adj thermal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 15:00
3	620	(rta or rapid adj thermal) near4 apparatus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 15:41
4	162	(rta or rapid adj thermal) near4 apparatus and (wafer or substrate or device) near3 (tray or holder or carrier or plate or chuck)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 15:41
-	10	(wafer or substrate) near2 tray and (tray near2 groove or slot or slit) and (rta or rtp or rapid adj thermal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 15:18
-	173	(tray or holder) near3 (alignment or aligning or positioning or positioned or position or groove or grooved) and (rta or rtp or rapid adj thermal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 15:21
-	16	(tray or holder) near3 (groove or grooved) and (rta or rtp or rapid adj thermal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 16:05
-	272	156/345.51.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 16:06
-	1548	(wafer or substrate) near2 (chuck or tray or holder or holding) and (chuck or tay or holder or holding) near2 (slot or slit or groove or notch)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 16:23
-	485	(wafer or substrate) near2 (chuck or tray or holder or holding) and (chuck or tay or holder or holding) near2 (slot or slit or groove or notch) and (rta or rtp or rapid adj thermal or wafer near2 position\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 16:26
-	62	(wafer or substrate) near2 boat and (rta or rtp or rapid adj thermal) and tube	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 16:44
-	10	("5109264" "5217340" "5310339" "5622639" "5662469" "5752609" "5786248" "5910218" "5956595" "6092537").PN.	USPAT	2003/06/10 16:34
-	1004	(rta or rtp or rapid adj thermal) and (wafer or substrate) near2 (position or positioning)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 16:45
-	294	(rta or rtp or rapid adj thermal) and (wafer or substrate) near2 (position or positioning) and (wafer or substrate) near3 (chuck or tray or holder or frame)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 17:08

-	1109	(wafer or substrate) near2 (holder or carrier or tray or chuck or support) and (holder or carrier or tray or chuck or support) near6 (slot or groove or slit or notch) near6 (position or positioning or securing or positioned or aligning or aligned)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 17:14
-	452	(wafer or substrate) near2 (holder or carrier or tray or chuck or support) and (holder or carrier or tray or chuck or support) near3 (slot or groove or slit or notch) near3 (position or positioning or securing or positioned or aligning or aligned)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 17:16
-	234	(wafer or substrate) near2 (holder or carrier or tray or chuck or support) and (holder or carrier or tray) near3 (slot or groove or slit or notch) near3 (position or positioning or securing or positioned or aligning or aligned)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 17:17
-	42	(rta or rtp or rapid near thermal) and (wafer or substrate) near2 (holder or carrier or tray or chuck or support) and (holder or carrier or tray or chuck or support) near3 (square or rectangle or rectangular or corner)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:04
-	1	(wafer or substrate) near2 (holder or carrier or tray or chuck or support) same (position or positioning) near3 kit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:05
-	718	(position or positioning) near3 kit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:05
-	16	(position or positioning) near3 kit near6 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:10
-	0	(position or positioning) adj3 kit near6 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:11
-	307	(position or positioning) adj3 kit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:12
-	91	(position or positioning) adj kit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:12
-	153	438/663.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:37